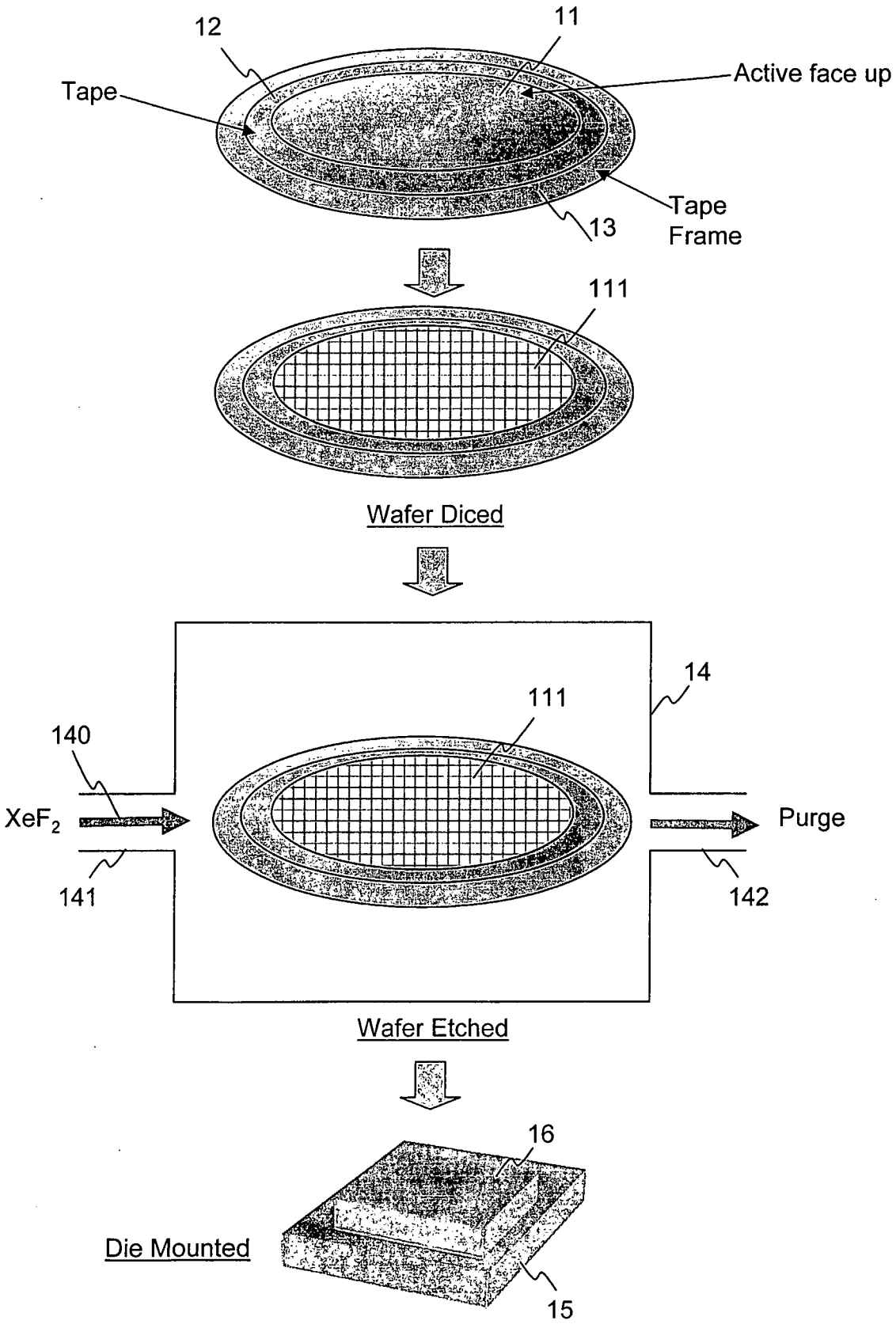

12
11
Tape
Active face up
Tape
Frame
13
111
Wafer Diced
14
111
140
XeF_2
Purge
141
142
Wafer Etched
16
Die Mounted
15

Figure 1

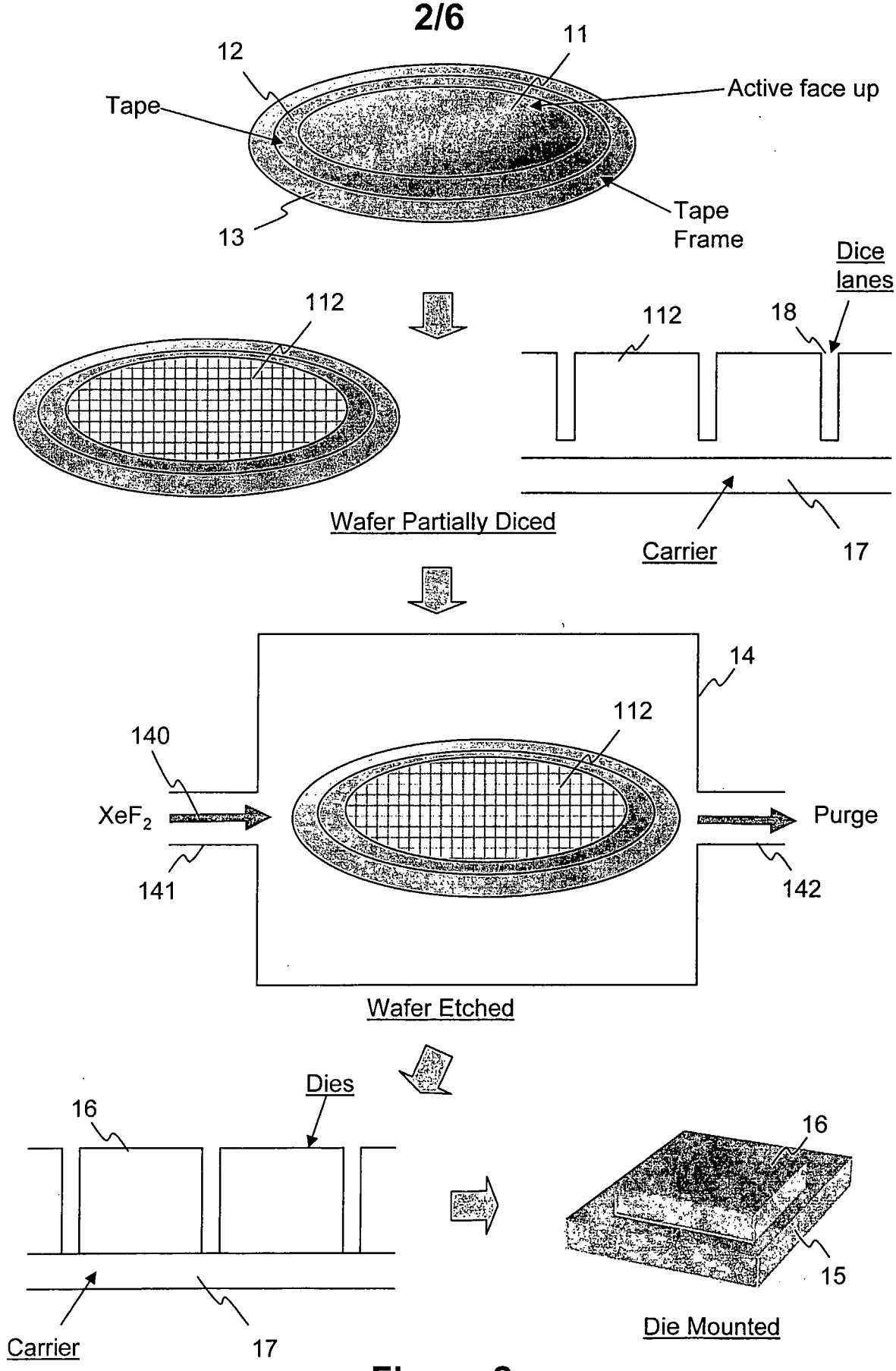

12
11
Tape
Active face up
13
Tape
Frame
Dice
lanes
112
112
18
Wafer Partially Diced
Carrier
17
14
112
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Purge
141
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Wafer Etched
Dies
16
16
Carrier
17
15
Die Mounted

Figure 2

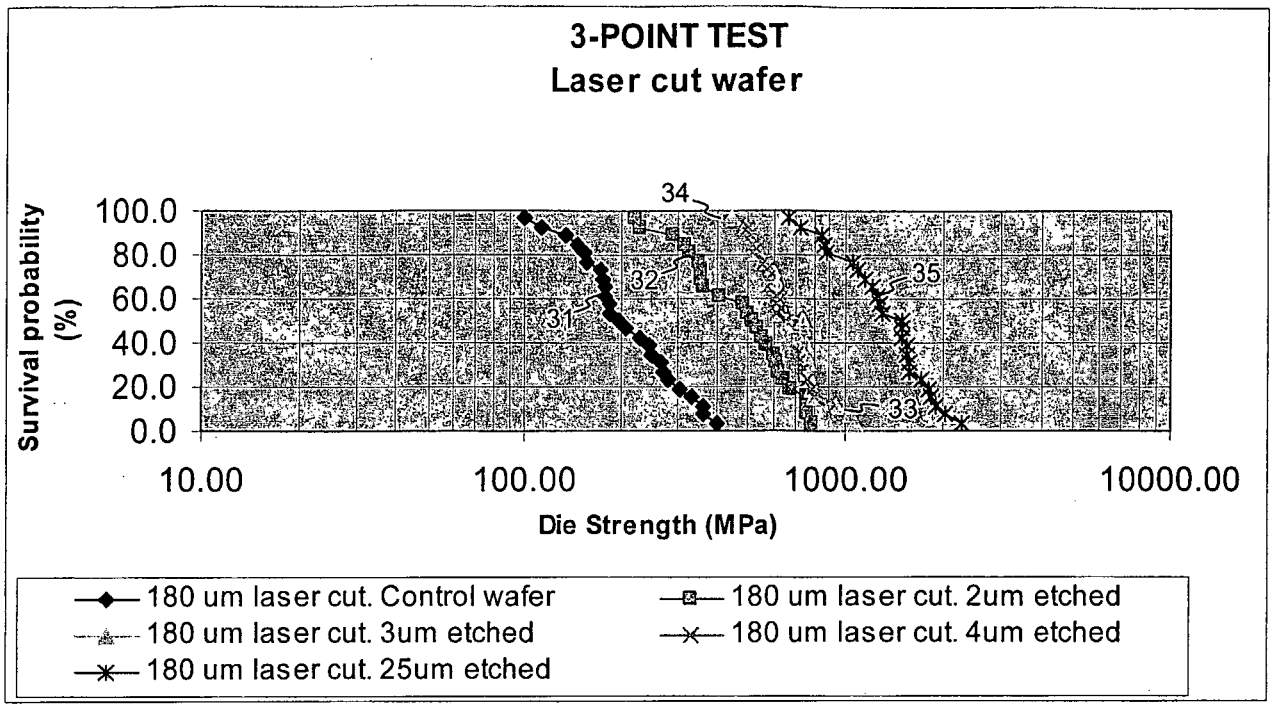


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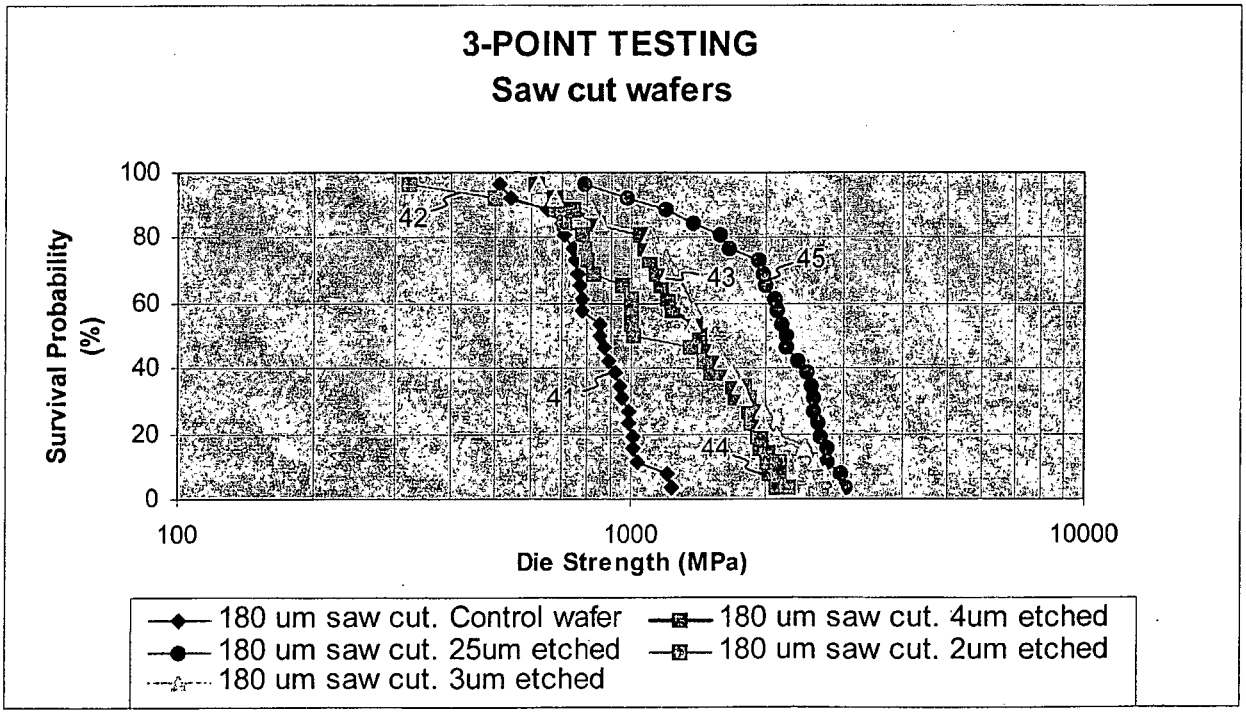


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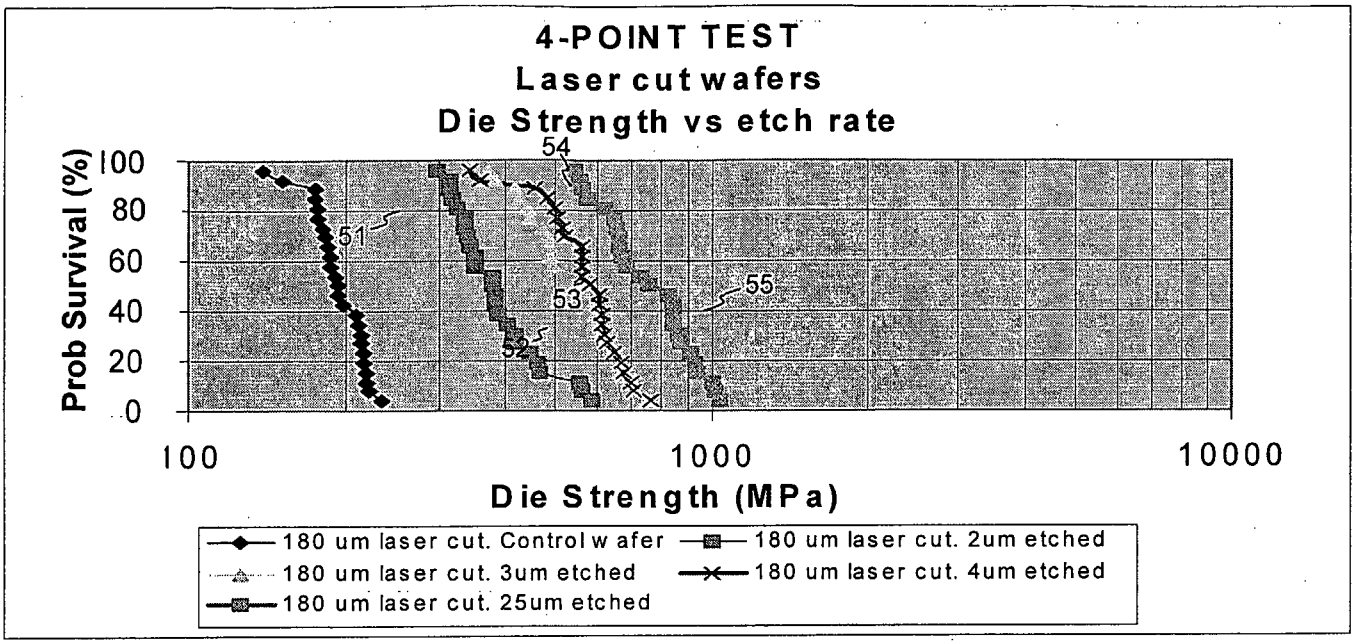


Figure 5

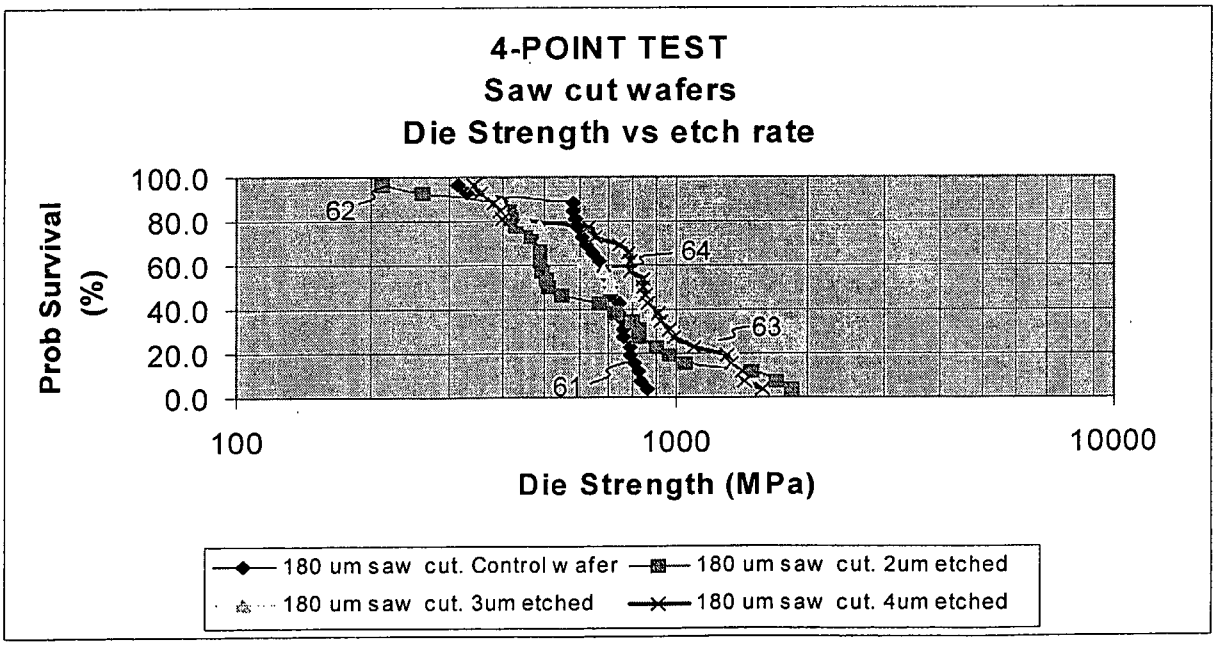


Figure 6

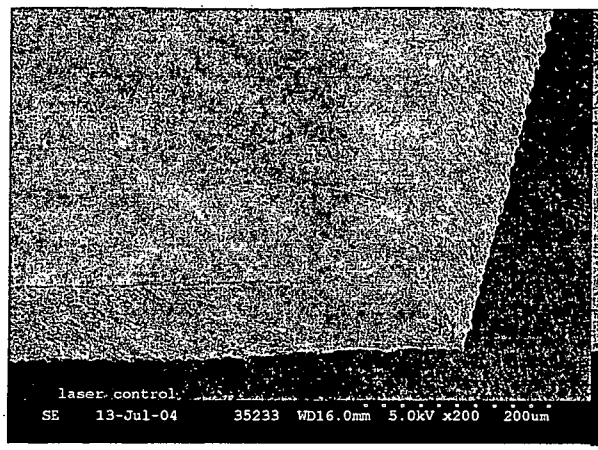


Figure 7(a)

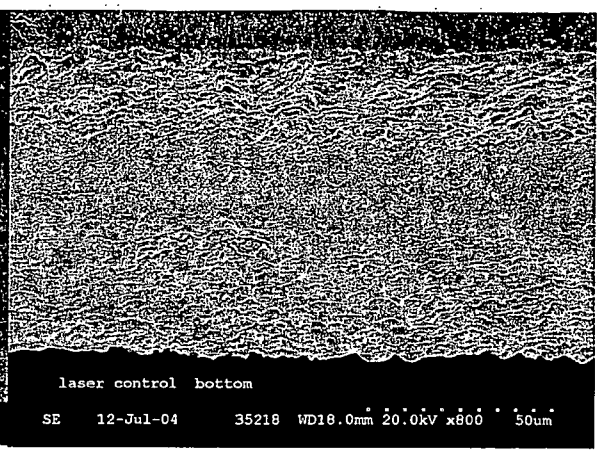


Figure 7(b)

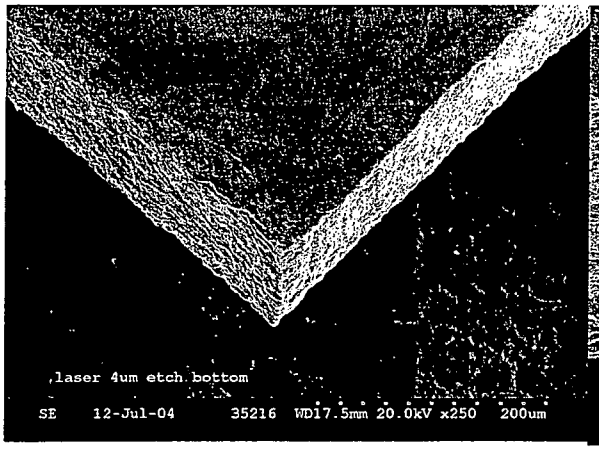


Figure 7(c)

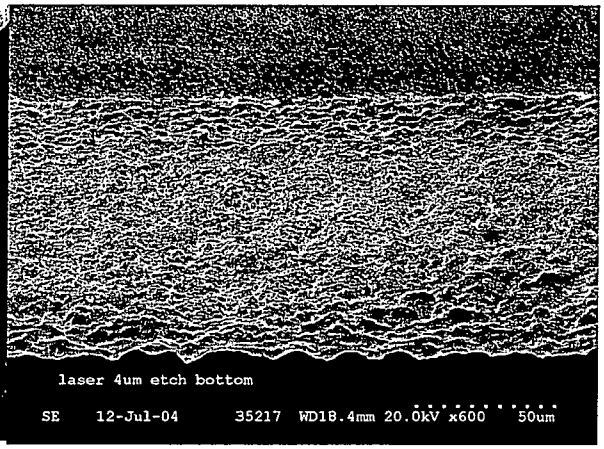


Figure 7(d)

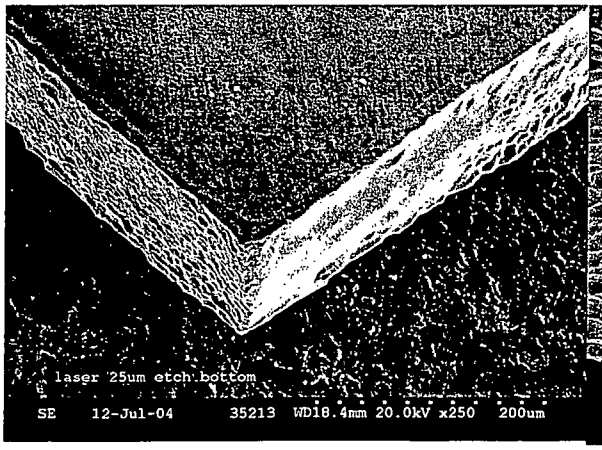


Figure 7(e)

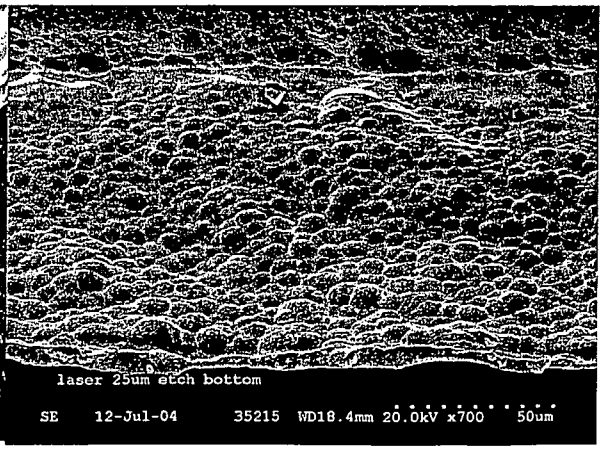


Figure 7(f)

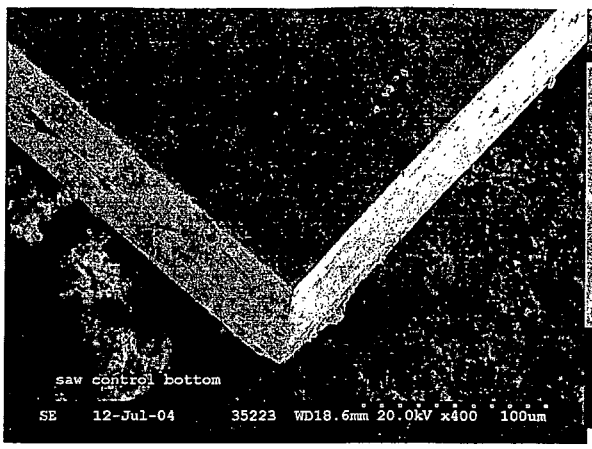


Figure 8(a)

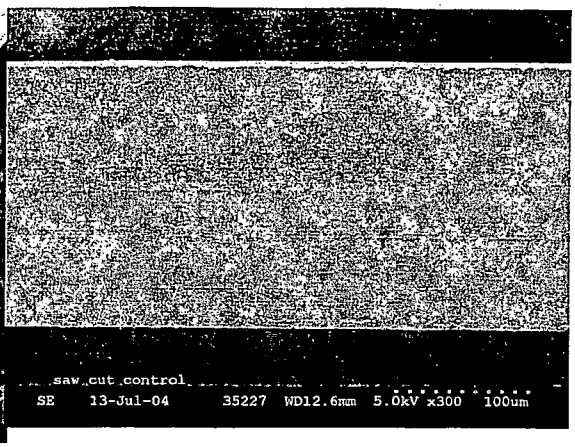


Figure 8(b)

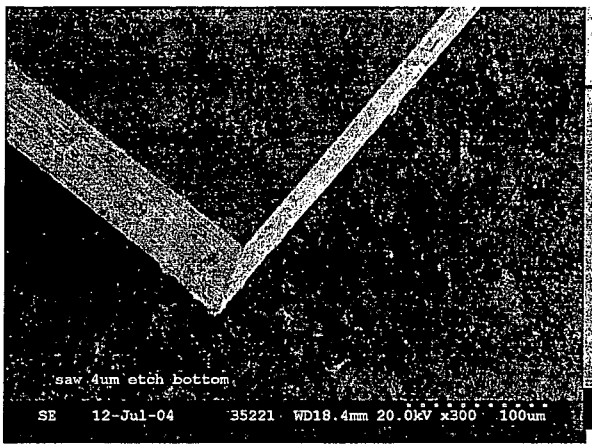


Figure 8(c)

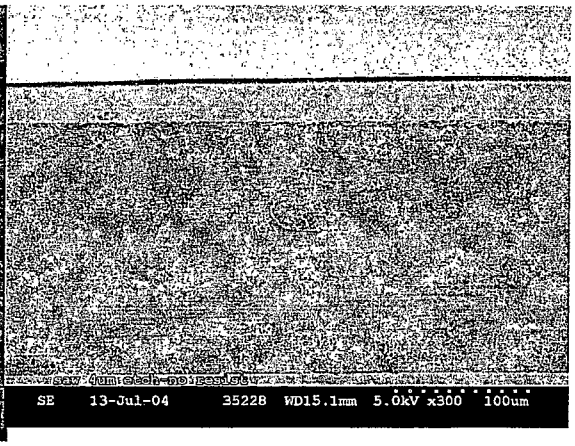


Figure 8(d)

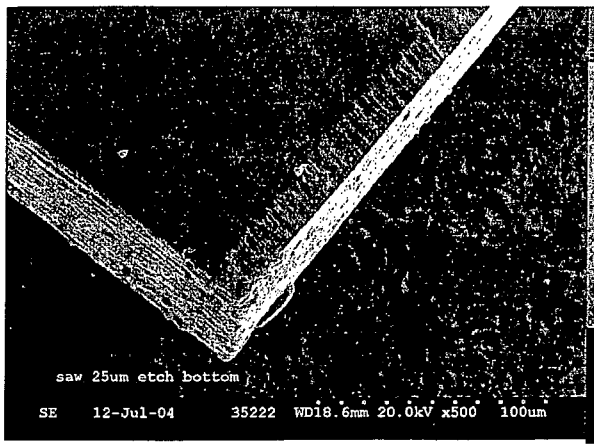


Figure 8(e)

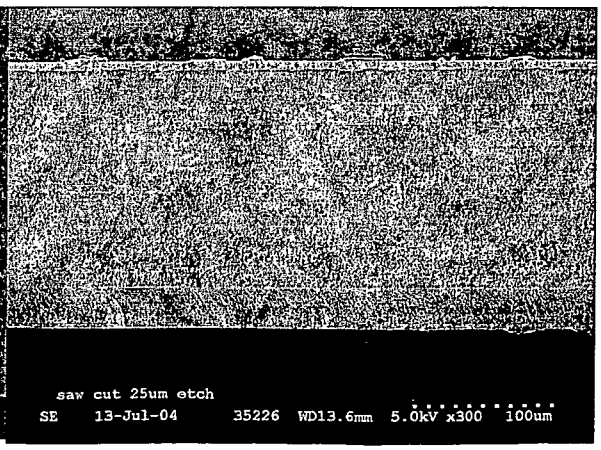


Figure 8(f)